

FCP20N60 / FCPF20N60

N-Channel SuperFET[®] MOSFET

600 V, 20 A, 190 mΩ

Features

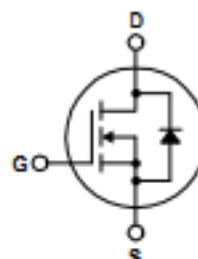
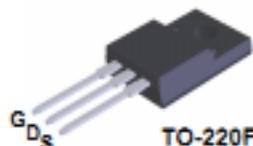
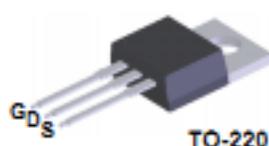
- 650V @ $T_J = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 160\text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 75\text{ nC}$)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)} = 165\text{ pF}$)
- 100% Avalanche Tested

Applications

- Solar Inverter
- AC-DC Power Supply

Description

SuperFET[®] MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.



Absolute Maximum Ratings

Symbol	Parameter	FCP20N60	FCPF20N60	Unit
V_{DSS}	Drain-Source Voltage	600		V
I_D	Drain Current	• Continuous ($T_C = 25^{\circ}\text{C}$)	20	20*
		• Continuous ($T_C = 100^{\circ}\text{C}$)	12.5	12.5*
I_{DM}	Drain Current	• Pulsed (Note 1)	80	80*
V_{GSS}	Gate-Source Voltage	± 30		V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	690		mJ
I_{AR}	Avalanche Current (Note 1)	20		A
E_{AR}	Repetitive Avalanche Energy (Note 1)	20.8		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5		V/ns
P_D	Power Dissipation ($T_C = 25^{\circ}\text{C}$)	• Derate Above 25°C	208	39
			1.67	0.3
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150		$^{\circ}\text{C}$
T_L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300		$^{\circ}\text{C}$

*Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FCP20N60	FCPF20N60	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.8	3.2	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^{\circ}\text{C}/\text{W}$

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP20N60	FCP20N60	TO-220	Tube	N/A	N/A	50 units
FCPF20N60	FCPF20N60	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}, T_J = 25^\circ\text{C}$	600	-	-	V
		$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{ V}, T_J = 150^\circ\text{C}$	-	650	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	-	0.6	-	V/ $^\circ\text{C}$
BV_{DS}	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 20 \text{ A}$	-	700	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μA
		$V_{DS} = 480 \text{ V}, T_C = 125^\circ\text{C}$	-	-	10	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	0.15	0.19	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_D = 10 \text{ A}$	-	17	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	2370	3080	pF
C_{oss}	Output Capacitance		-	1280	1665	pF
C_{rss}	Reverse Transfer Capacitance		-	95	-	pF
C_{oss}	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	65	65	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$	-	165	-	pF
Q_g	Total Gate Charge at 10V	$V_{DS} = 480 \text{ V}, I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}$	-	75	98	nC
Q_{gs}	Gate to Source Gate Charge		-	13.5	18	nC
Q_{gd}	Gate to Drain "Miller" Charge		(Note 4)	-	38	-

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 300 \text{ V}, I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 25 \Omega$	-	62	135	ns	
t_r	Turn-On Rise Time		-	140	290	ns	
$t_{d(off)}$	Turn-Off Delay Time		(Note 4)	-	230	470	ns
t_f	Turn-Off Fall Time		-	65	140	ns	

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	20	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	60	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{SD} = 20 \text{ A}$	-	-	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{SD} = 20 \text{ A}$	-	530	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt = 100 \text{ A}/\mu\text{s}$	-	10.5	-	μC

Notes:

- 1: Repetitive rating; pulse-width limited by maximum junction temperature.
- 2: $I_{SD} = 10 \text{ A}, V_{DD} = 50 \text{ V}, R_G = 25 \Omega$, starting $T_J = 25^\circ\text{C}$.
- 3: $I_{SD} \leq 20 \text{ A}$, di/dt $\leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, starting $T_J = 25^\circ\text{C}$.
- 4: Essentially independent of operating temperature typical characteristics.